



Data sheet acquired from Harris Semiconductor
SCHS211E

CD54HC4094, CD74HC4094, CD74HCT4094

High-Speed CMOS Logic

November 1997 – Revised December 2010

8-Stage Shift and Store Bus Register, Three-State

Features

- ¥ Buffered Inputs
- ¥ Separate Serial Outputs Synchronous to Both Positive and Negative Clock Edges For Cascading
- ¥ Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- ¥ Wide Operating Temperature Range . . . –55°C to 125°C
- ¥ Balanced Propagation Delay and Transition Times
- ¥ Significant Power Reduction Compared to LSTTL Logic ICs
- ¥ HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- ¥ HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

Description

The CD54HC4094 and CD74HCT4094 are 8-stage serial shift registers having a storage latch associated with each stage for strobing data from the serial input to parallel buffered three-state outputs. The parallel outputs may be connected directly to common bus lines. Data is shifted on positive clock transitions. The data in each shift register stage is transferred to the storage register when the Strobe input is high. Data in the storage register appears at the outputs whenever the Output-Enable signal is high.

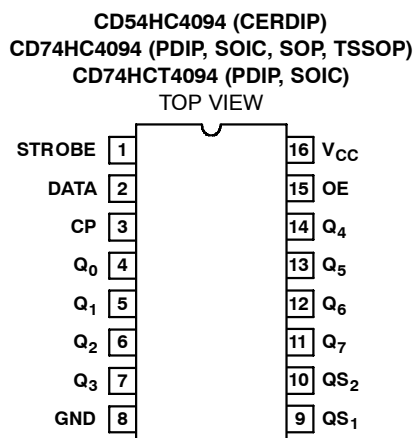
Two serial outputs are available for cascading a number of these devices. Data is available at the QS_1 serial output terminal on positive clock edges to allow for high-speed operation in cascaded system in which the clock rise time is fast. The same serial information, available at the QS_2 terminal on the next negative clock edge, provides a means for cascading these devices when the clock rise time is slow.

Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC4094F3A	–55 to 125	16 Ld CERDIP
CD74HC4094E	–55 to 125	16 Ld PDIP
CD74HC4094M	–55 to 125	16 Ld SOIC
CD74HC4094MT	–55 to 125	16 Ld SOIC
CD74HC4094M96G3	–55 to 125	16 Ld SOIC
CD74HC4094NSR	–55 to 125	16 Ld SOP
CD74HC4094PW	–55 to 125	16 Ld TSSOP
CD74HC4094PWR	–55 to 125	16 Ld TSSOP
CD74HC4094PWT	–55 to 125	16 Ld TSSOP
CD74HCT4094E	–55 to 125	16 Ld PDIP
CD74HCT4094M	–55 to 125	16 Ld SOIC
CD74HCT4094MT	–55 to 125	16 Ld SOIC
CD74HCT4094M96	–55 to 125	16 Ld SOIC

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

Pinout

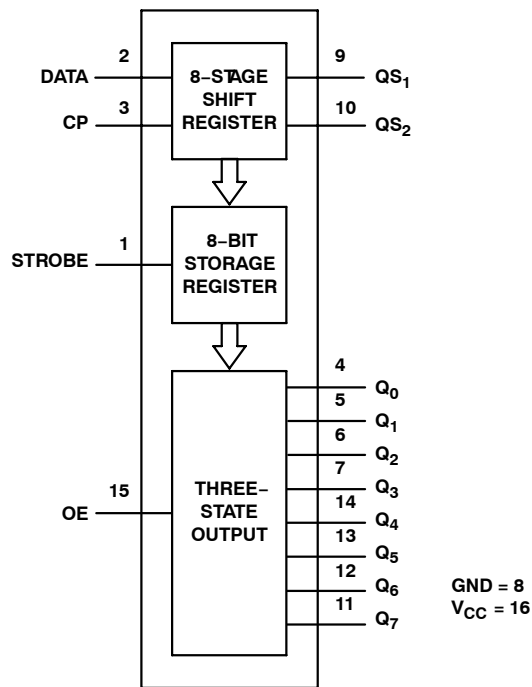


CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

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Functional Diagram



TRUTH TABLE

INPUTS				PARALLEL OUTPUTS		SERIAL OUTPUTS	
CP	OE	STR	D	Q ₀	Q _n	QS ₁ (NOTE 1)	QS ₂
↑	L	X	X	Z	Z	Q ₀ 6	NC
↓	L	X	X	Z	Z	NC	Q ₇
↑	H	L	X	NC	NC	Q ₀ 6	NC
↑	H	H	L	L	Q _n -1	Q ₀ 6	NC
↑	H	H	H	H	Q _n -1	Q ₀ 6	NC
↓	H	H	H	NC	NC	NC	Q ₇

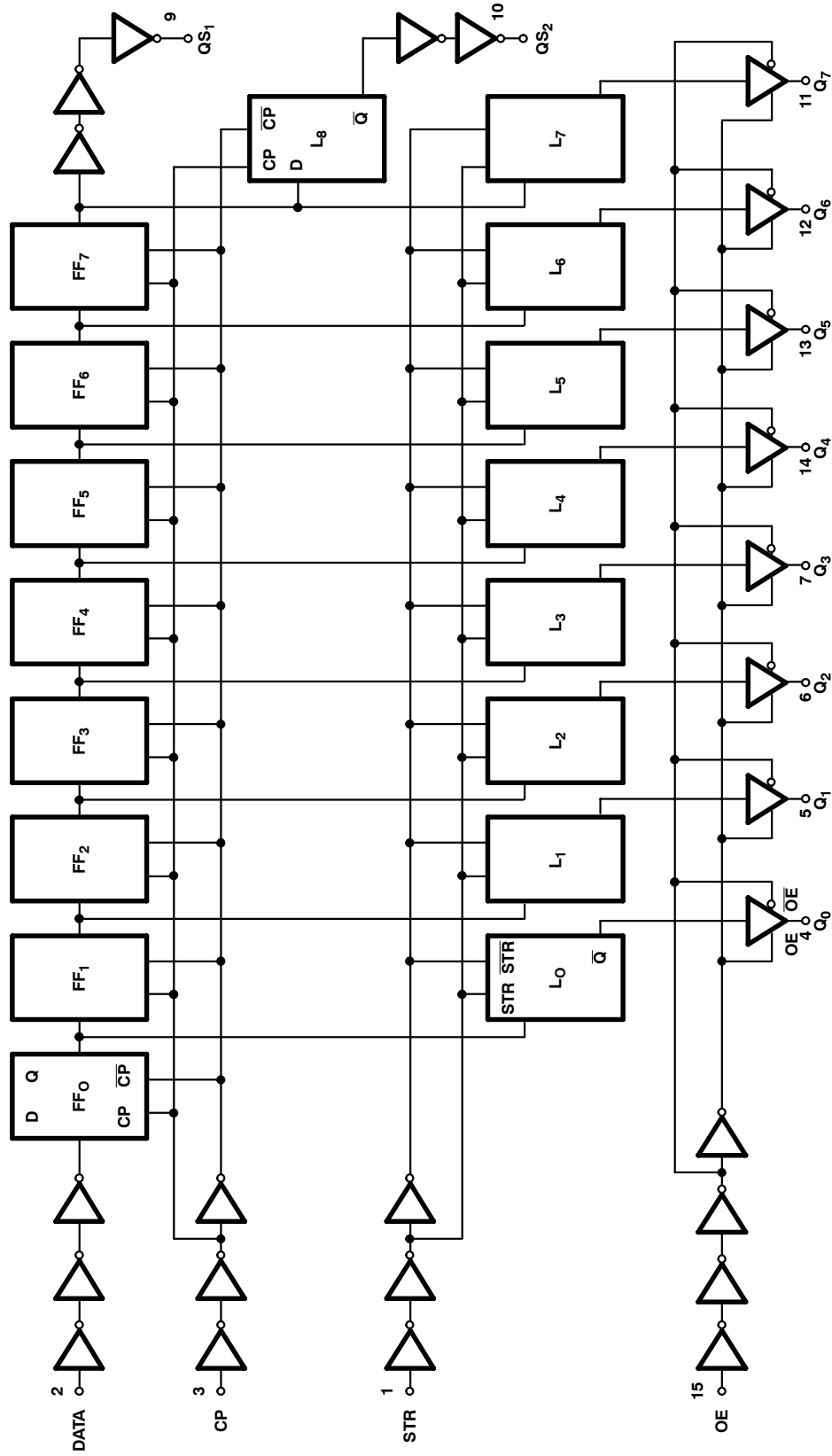
H = High Voltage Level, L = Low Voltage Level, X = Don't Care, NC = No charge, Z = High Impedance Off-state,
↑ = Transition from Low to High Level, ↓ = Transition from High to Low.

NOTE:

1. At the positive clock edge the information in the seventh register stage is transferred to the 8th register stage and QS1 output.

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Logic Diagram



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Absolute Maximum Ratings

DC Supply Voltage, V_{CC} -0.5V to 7V
DC Input Diode Current, I_{IK}
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ $\pm 20mA$
DC Output Diode Current, I_{OK}
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ $\pm 20mA$
DC Output Source or Sink Current per Output Pin, I_O
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ $\pm 25mA$
DC V_{CC} or Ground Current, I_{CC} $\pm 50mA$

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 2):
E (PDIP) Package $67^{\circ}C/W$
M (SOIC) Package $73^{\circ}C/W$
NS (SOP) Package $64^{\circ}C/W$
PW (TSSOP) Package $108^{\circ}C/W$
Maximum Junction Temperature (Plastic Package) 150°
Maximum Storage Temperature Range $-65^{\circ}C$ to 150°
Maximum Lead Temperature (Soldering 10s) 300°
SOIC – Lead Tips Only)

Operating Conditions

Temperature Range (T_A) $-55^{\circ}C$ to $125^{\circ}C$
Supply Voltage Range, V_{CC}
HC Types 2V to 6V
HCT Types 4.5V to 5.5V
DC Input or Output Voltage, V_I , V_O 0V to V_{CC}
Input Rise and Fall Time
2V 1000ns (Max)
4.5V 500ns (Max)
6V 400ns (Max)

CAUTION: Stresses above those listed in Absolute Maximum Ratings may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

2. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS		
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX			
HC TYPES														
High Level Input Voltage	V _{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V		
				4.5	3.15	-	-	3.15	-	3.15	-	V		
				6	4.2	-	-	4.2	-	4.2	-	V		
Low Level Input Voltage	V _{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V		
				4.5	-	-	1.35	-	1.35	-	1.35	V		
				6	-	-	1.8	-	1.8	-	1.8	V		
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V		
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V		
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V		
-			-	-	-	-	-	-	-	-	V			
-4			4.5	3.98	-	-	3.84	-	3.7	-	V			
-5.2			6	5.48	-	-	5.34	-	5.2	-	V			
High Level Output Voltage TTL Loads	V _{OL}	V _{IH} or V _{IL}	-	-	-	-	-	-	-	-	-	V		
			4	4.5	-	-	0.26	-	0.33	-	0.4	V		
			5.2	6	-	-	0.26	-	0.33	-	0.4	V		
0.02			2	-	-	0.1	-	0.1	-	0.1	V			
0.02			4.5	-	-	0.1	-	0.1	-	0.1	V			
0.02			6	-	-	0.1	-	0.1	-	0.1	V			
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	-	-	-	-	-	-	-	-	-	V		
			4	4.5	-	-	0.26	-	0.33	-	0.4	V		
			5.2	6	-	-	0.26	-	0.33	-	0.4	V		
Input Leakage Current			I _I	V _{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current			I _{CC}	V _{CC} or GND	0	6	-	-	8	-	80	-	160	µA

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DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES												
High Level Input Voltage	V _{IH}	–	–	4.5 to 5.5	2	–	–	2	–	2	–	V
Low Level Input Voltage	V _{IL}	–	–	4.5 to 5.5	–	–	0.8	–	0.8	–	0.8	V
High Level Output Voltage CMOS Loads	V _{OH}	V _{IH} or V _{IL}	–0.02	4.5	4.4	–	–	4.4	–	4.4	–	V
High Level Output Voltage TTL Loads			–4	4.5	3.98	–	–	3.84	–	3.7	–	V
Low Level Output Voltage CMOS Loads	V _{OL}	V _{IH} or V _{IL}	0.02	4.5	–	–	0.1	–	0.1	–	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	–	–	0.26	–	0.33	–	0.4	V
Input Leakage Current	I _I	V _{CC} and GND	0	5.5	–	–	±0.1	–	±1	–	±1	μA
Quiescent Device Current	I _{CC}	V _{CC} or GND	0	5.5	–	–	8	–	80	–	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI _{CC} (Note 3)	V _{CC} –2.1	–	4.5 to 5.5	–	100	360	–	450	–	490	μA

NOTE:

3. For dual-supply systems theoretical worst case (V = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
D	0.4
CP, OE	1.5
STR	1.0

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

Prerequisite for Switching Specifications

CHARACTERISTIC	SYMBOL	V _{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	MIN	MAX	
HC TYPES									
CP Pulse Width	t _W	2	80	–	100	–	120	–	ns
		4.5	16	–	20	–	24	–	ns
		6	14	–	17	–	20	–	ns
STR Pulse Width	t _{WH}	2	80	–	100	–	120	–	ns
		4.5	16	–	20	–	24	–	ns
		6	14	–	17	–	20	–	ns

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Prerequisite for Switching Specifications (Continued)

CHARACTERISTIC	SYMBOL	V _{CC} (V)	25°C		–40°C TO 85°C		–55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	MIN	MAX	
Data Set-up Time	t _{SU}	2	50	–	65	–	75	–	ns
		4.5	10	–	13	–	15	–	ns
		6	9	–	11	–	13	–	ns
Data Hold Time	t _H	2	3	–	3	–	3	–	ns
		4.5	3	–	3	–	3	–	ns
		6	3	–	3	–	3	–	ns
STR Set-up Time	t _{SU}	2	100	–	125	–	150	–	ns
		4.5	20	–	25	–	30	–	ns
		6	17	–	21	–	26	–	ns
STR Hold Time	t _H	2	0	–	0	–	0	–	ns
		4.5	0	–	0	–	0	–	ns
		6	0	–	0	–	0	–	ns
Maximum CP Frequency	f _{CL} (MAX)	2	6	–	5	–	4	–	MHz
		4.5	30	–	24	–	20	–	MHz
		6	35	–	28	–	24	–	MHz

HCT TYPES

CP Pulse Width	t _W	4.5	16	–	20	–	24	–	ns
STR Pulse Width	t _{WH}	4.5	16	–	20	–	24	–	ns
Data Set-up Time	t _{SU}	4.5	10	–	13	–	15	–	ns
Data Hold Time	t _H	4.5	4	–	4	–	4	–	ns
STR Set-up Time	t _{SU}	4.5	20	–	25	–	30	–	ns
STR Hold Time	t _H	4.5	0	–	0	–	0	–	ns
Maximum CP Frequency	f _{CL} (MAX)	4.5	30	–	24	–	20	–	MHz

Switching Specifications Input t_p, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V _{CC} (V)	25°C			–40°C TO 85°C		–55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay Time (Figure 1) CP to QS ₁	t _{PLH} , t _{PHL}	C _L = 50pF	2	–	–	150	–	190	–	225	ns
			4.5	–	–	30	–	38	–	45	ns
		C _L =15pF	5	–	12	–	–	–	–	–	ns
		C _L = 50pF	6	–	–	26	–	33	–	38	ns
CP to QS ₂	t _{PLH} , t _{PHL}	C _L = 50pF	2	–	–	135	–	170	–	205	ns
			4.5	–	–	27	–	34	–	41	ns
		C _L =15pF	5	–	11	–	–	–	–	–	ns
		C _L = 50pF	6	–	–	23	–	29	–	35	ns
CP to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	2	–	–	195	–	245	–	295	ns
			4.5	–	–	39	–	49	–	59	ns
			5	–	16	–	–	–	–	–	ns
			6	–	–	33	–	42	–	50	ns
STR to Q _n	t _{PLH} , t _{PHL}	C _L = 50pF	2	–	–	180	–	225	–	270	ns
			4.5	–	–	36	–	45	–	54	ns
			6	–	–	31	–	38	–	46	ns

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Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Output Enable to Q_n	t_{PZH}, t_{PZL}	$C_L = 50\text{pF}$	2	–	–	175	–	220	–	265	ns
			4.5	–	–	35	–	44	–	53	ns
			6	–	–	30	–	37	–	45	ns
Output Disable to Q_n	t_{PHZ}, t_{PLZ}	$C_L = 50\text{pF}$	2	–	–	125	–	155	–	190	ns
			4.5	–	–	25	–	31	–	38	ns
			6	–	–	21	–	26	–	32	ns
Output Transition Time	t_{TLH}, t_{THL}	$C_L = 50\text{pF}$	2	–	–	75	–	95	–	110	ns
			4.5	–	–	15	–	19	–	22	ns
			6	–	–	13	–	16	–	19	ns
Output Disabling Time	t_{PHZ}, t_{PLZ}	$C_L = 15\text{pF}$	5	–	10	–	–	–	–	–	ns
Maximum CP Frequency	f_{MAX}	$C_L = 15\text{pF}$	5	–	60	–	–	–	–	–	MHz
Input Capacitance	C_{IN}	$C_L = 50\text{pF}$	–	–	–	10	–	10	–	10	pF
Power Dissipation Capacitance (Notes 4, 5)	C_{PD}	$C_L = 15\text{pF}$	5	–	90	–	–	–	–	–	pF
Three-State Output Capacitance	C_O	$C_L = 50\text{pF}$	–	–	–	15	–	15	–	15	pF
HCT TYPES											
Propagation Delay Time (Figure 1)	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	4.5	–	–	39	–	–	–	–	ns
		$C_L = 15\text{pF}$	5	–	16	–	–	–	–	–	ns
CP to QS_1	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	4.5	–	–	36	–	–	–	–	ns
		$C_L = 15\text{pF}$	5	–	15	–	–	–	–	–	ns
CP to QS_2	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	4.5	–	–	36	–	–	–	–	ns
		$C_L = 15\text{pF}$	5	–	15	–	–	–	–	–	ns
CP to Q_n	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	4.5	–	–	43	–	–	–	–	ns
		$C_L = 15\text{pF}$	5	–	18	–	–	–	–	–	ns
STR to Q_n	t_{PLH}, t_{PHL}	$C_L = 50\text{pF}$	4.5	–	–	39	–	–	–	–	ns
Output Enable to Q_n	t_{PZH}, t_{PZL}	$C_L = 50\text{pF}$	4.5	–	–	35	–	–	–	–	ns
Output Disable to Q_n	t_{PHZ}, t_{PLZ}	$C_L = 50\text{pF}$	4.5	–	–	35	–	–	–	–	ns
Output Transition Time	t_{TLH}, t_{THL}	$C_L = 50\text{pF}$	4.5	–	–	15	–	–	–	–	ns
Output Disabling Time	t_{PHZ}, t_{PLZ}	$C_L = 15\text{pF}$	5	–	14	–	–	–	–	–	ns
Maximum CP Frequency	f_{MAX}	$C_L = 15\text{pF}$	5	–	60	–	–	–	–	–	MHz
Input Capacitance	C_{IN}	$C_L = 50\text{pF}$	–	–	–	10	–	10	–	10	pF
Power Dissipation Capacitance (Notes 4, 5)	C_{PD}	$C_L = 15\text{pF}$	5	–	110	–	–	–	–	–	pF
Three-State Output Capacitance	C_O	$C_L = 50\text{pF}$	–	–	–	15	–	15	–	15	pF

NOTES:

- C_{PD} is used to determine the dynamic power consumption, per register.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where f_i = Input Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

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Test Circuits and Waveforms

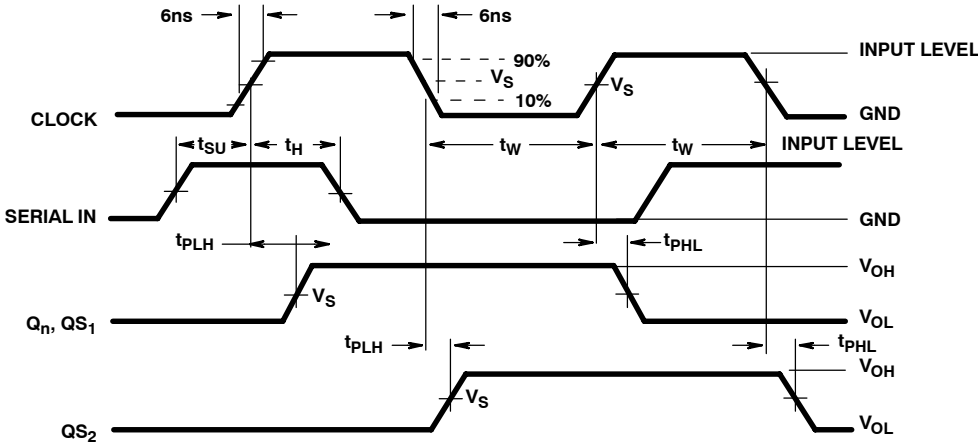


FIGURE 1. DATA PROPAGATION DELAYS, SET-UP AND HOLD TIMES

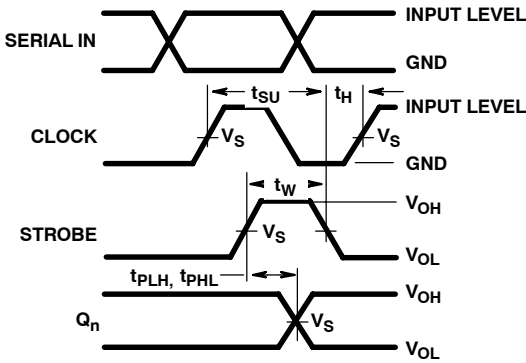


FIGURE 2. STROBE PROPAGATION DELAYS AND SET-UP AND HOLD TIMES

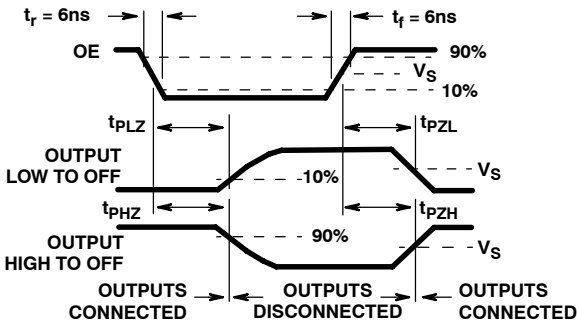


FIGURE 3. ENABLE AND DISABLE TIMES

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
CD54HC4094F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD74HC4094E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC4094EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC4094M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094M96G3	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
CD74HC4094M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
CD74HC4094PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PWRG3	PREVIEW	TSSOP	PW	16	2000	TBD	Call TI	Call TI	
CD74HC4094PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC4094PWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT4094E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT4094EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT4094M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT4094M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT4094M96E4	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	
CD74HCT4094M96G4	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	
CD74HCT4094ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT4094MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT4094MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT4094MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
CD74HCT4094MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54HC4094, CD74HC4094 :

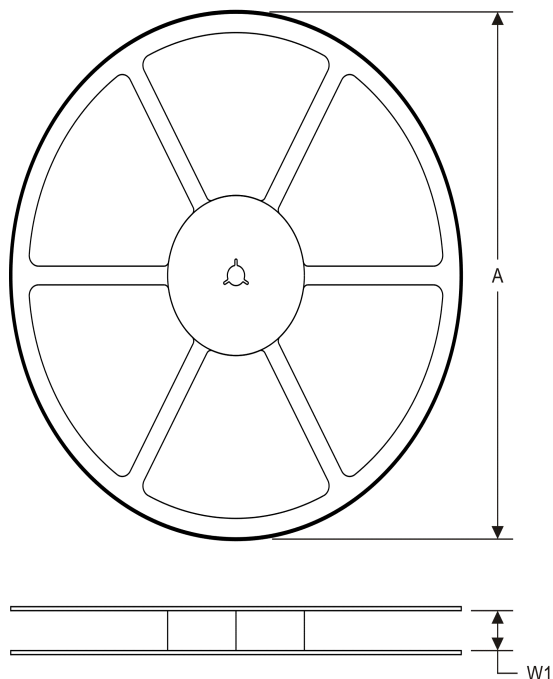
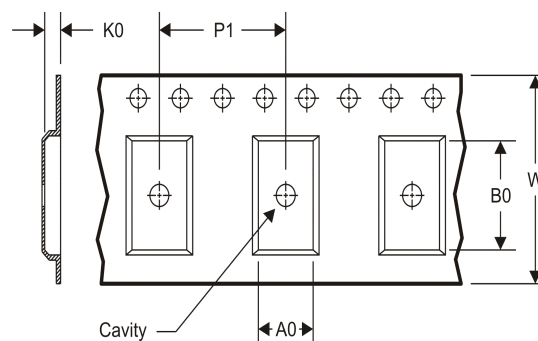
● Catalog: [CD74HC4094](#)

● Military: [CD54HC4094](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

-
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


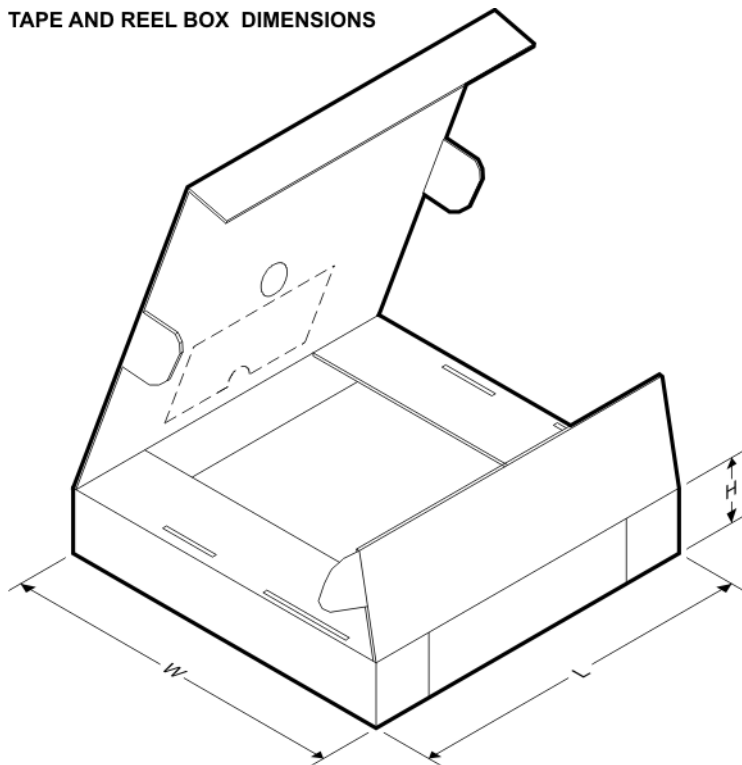
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4094M96G4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4094NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC4094PWR	TSSOP	PW	16	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
CD74HC4094PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4094PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4094PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



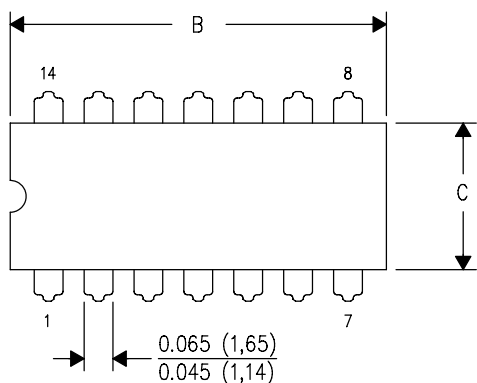
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4094M96G4	SOIC	D	16	2500	333.2	345.9	28.6
CD74HC4094NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HC4094PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
CD74HC4094PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
CD74HC4094PWRG4	TSSOP	PW	16	2000	367.0	367.0	35.0
CD74HC4094PWT	TSSOP	PW	16	250	367.0	367.0	35.0

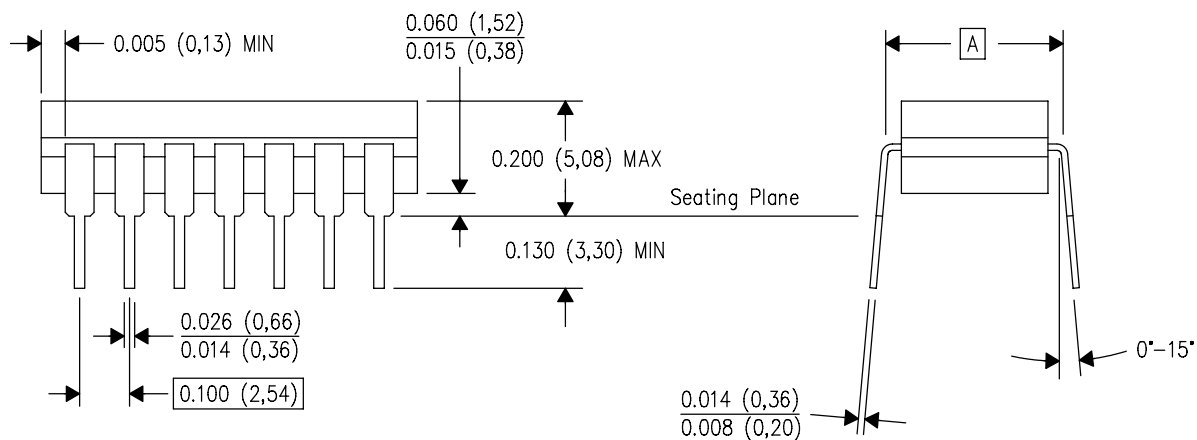
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



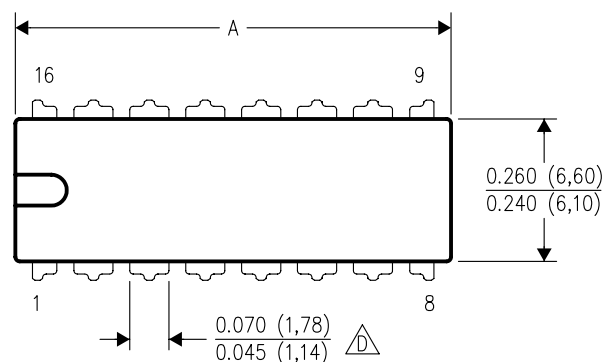
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

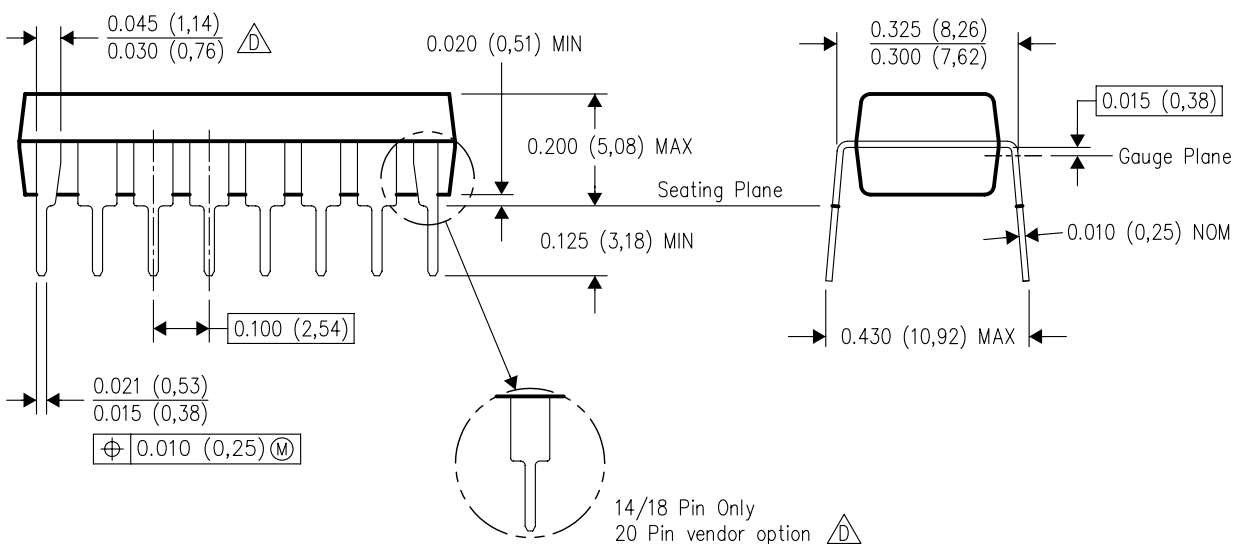
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



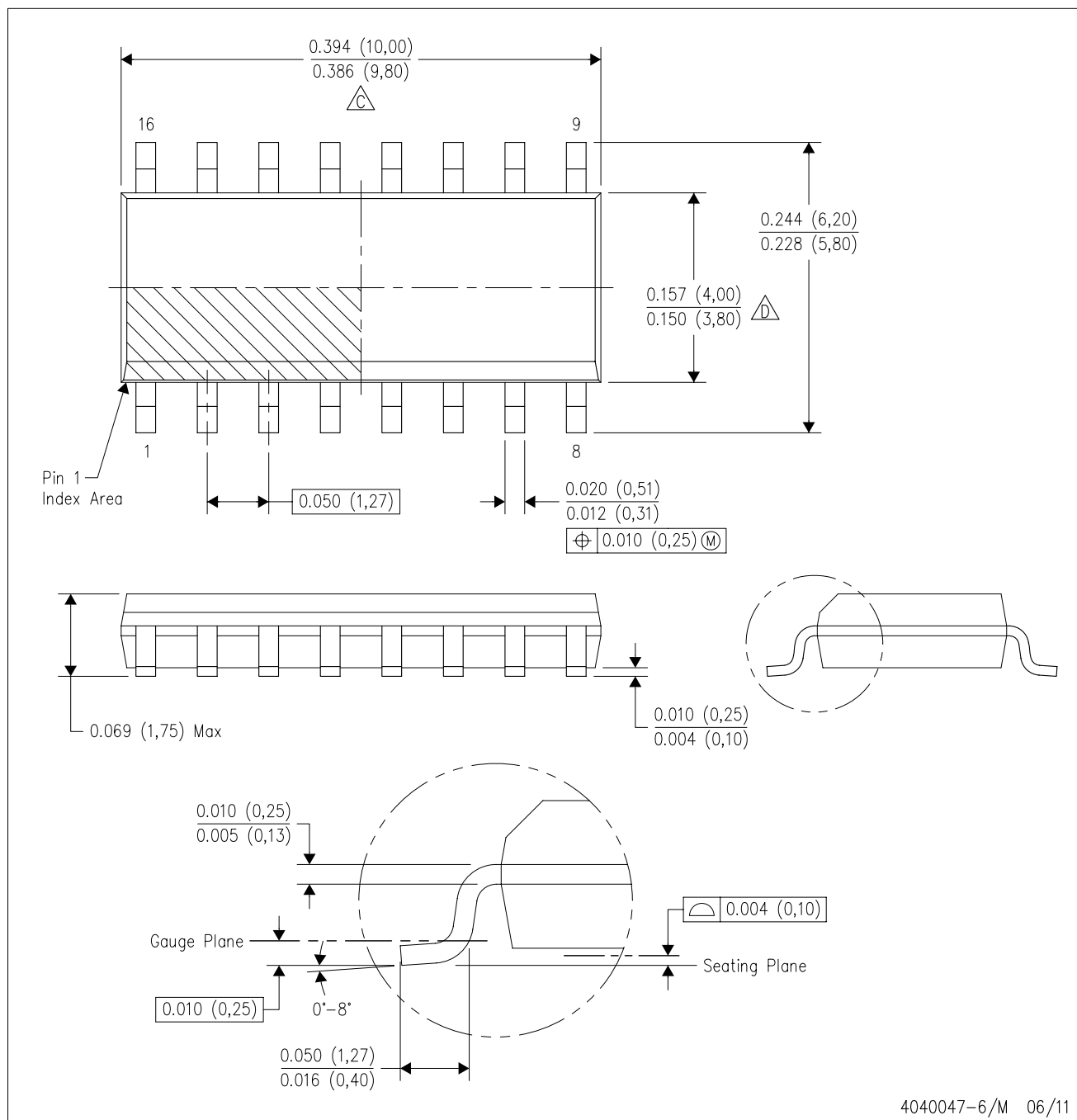
4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

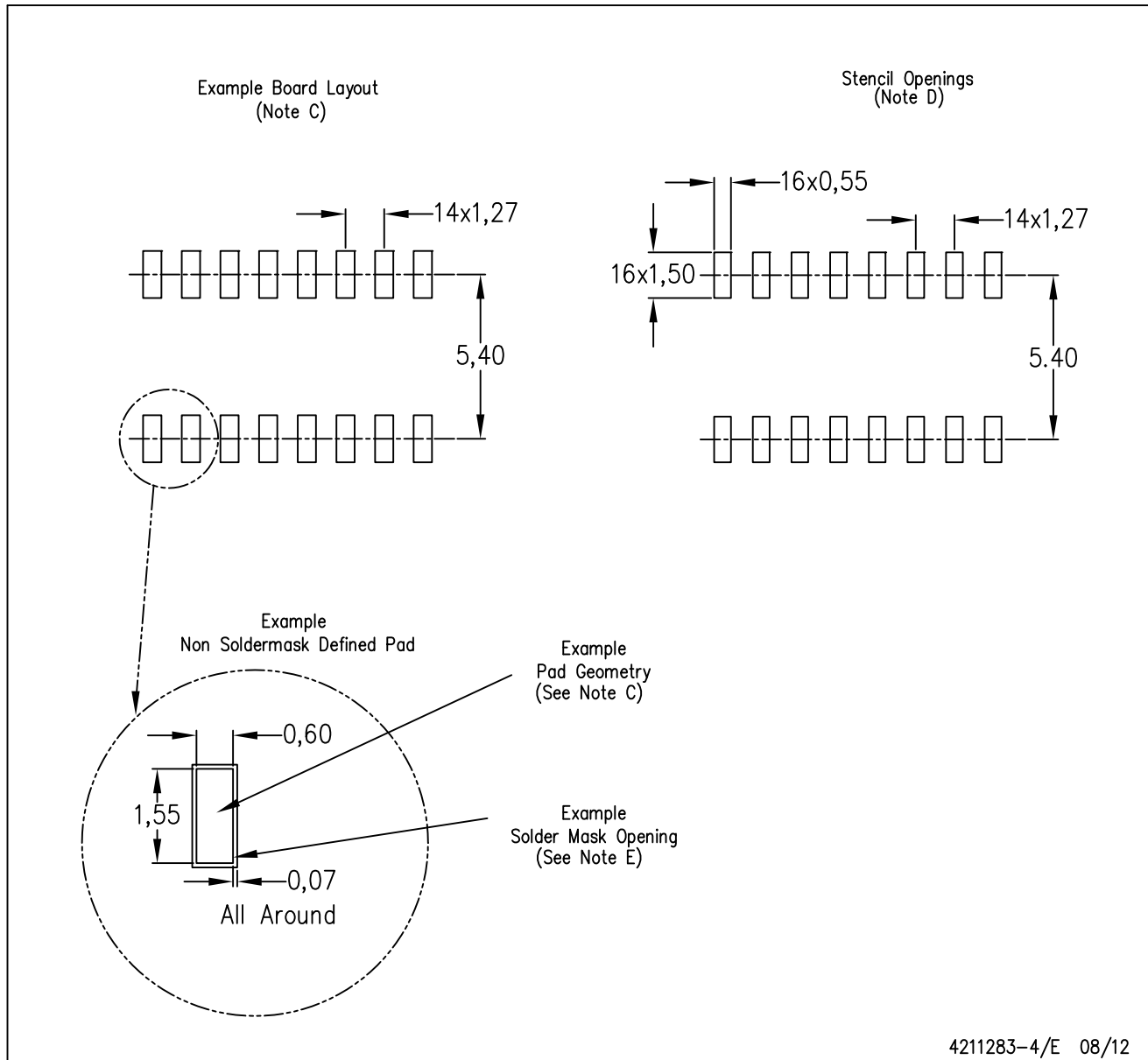


4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

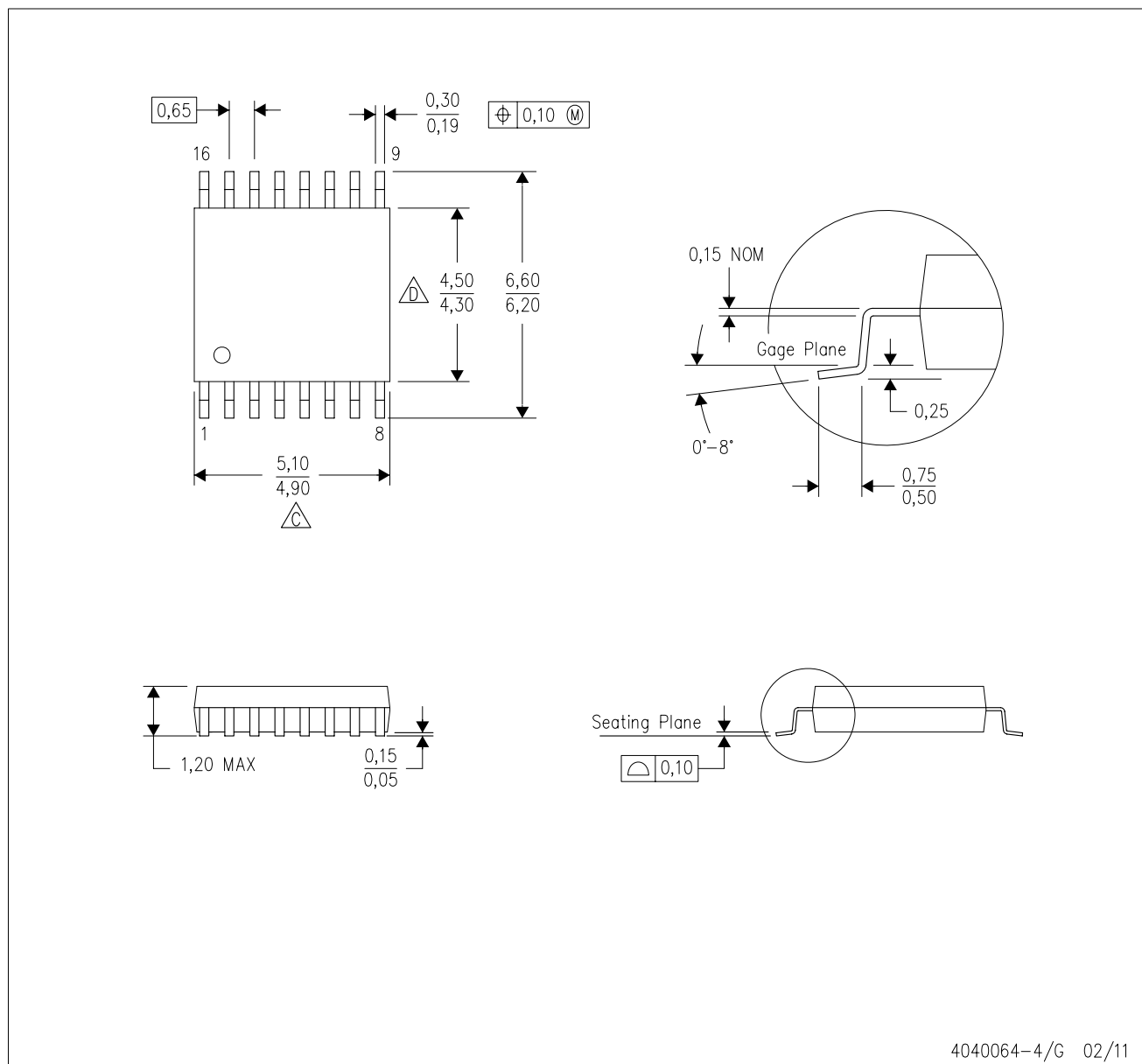
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G16)

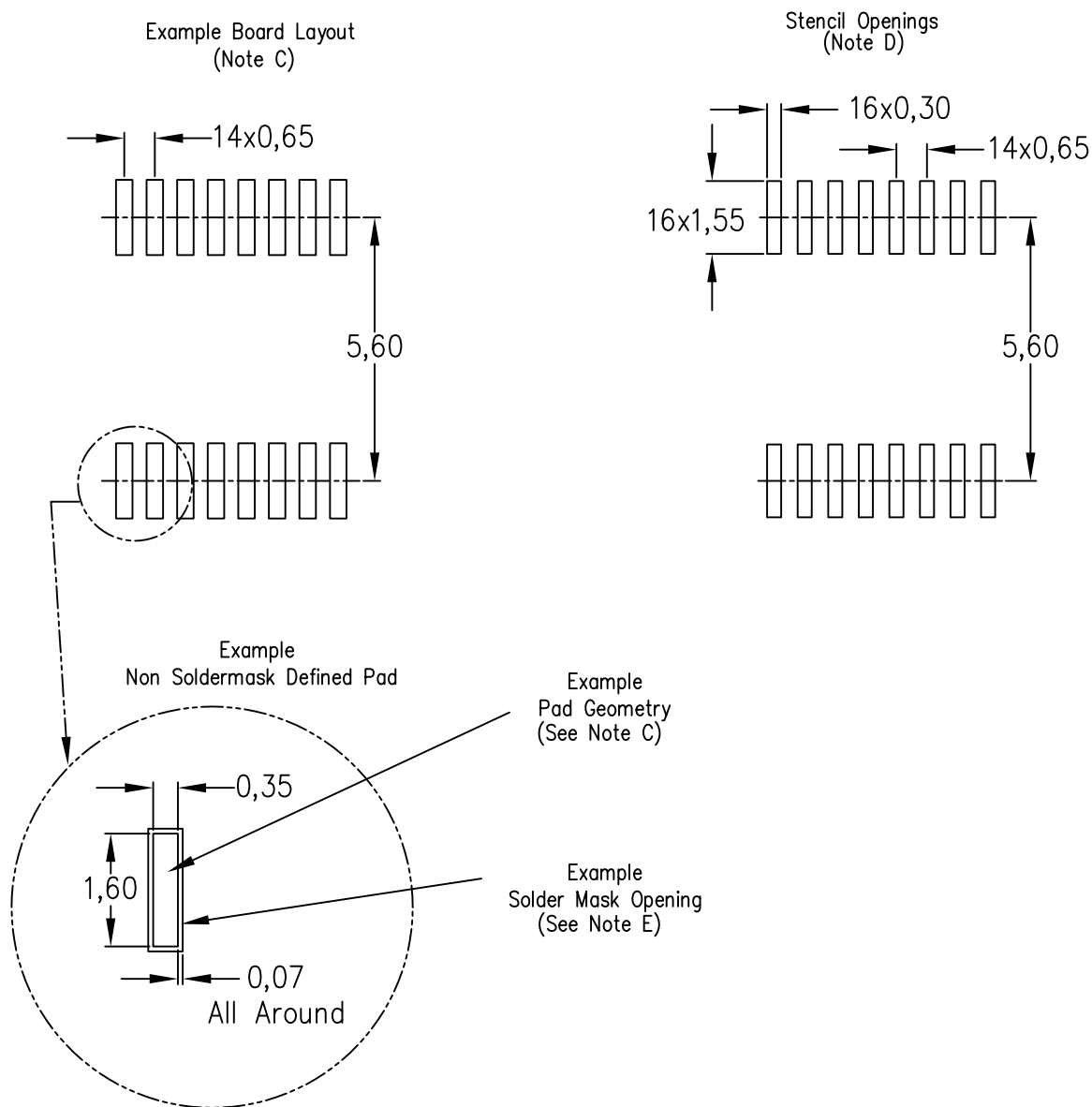
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - $\triangle$ C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - $\triangle$ D Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4211284-3/F 12/12

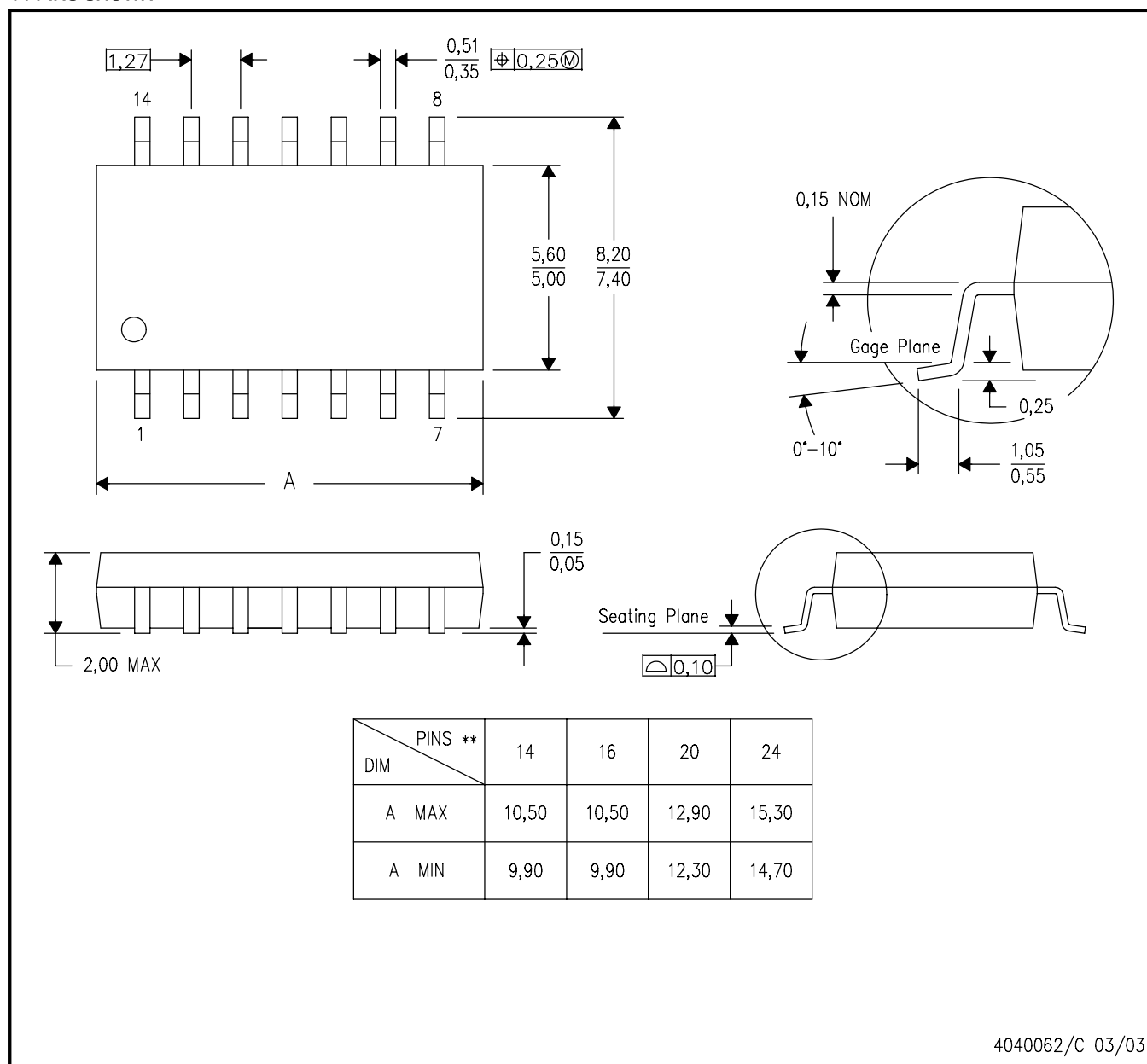
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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